

QUAD DIFFERENTIAL COMPARATOR

Check for Samples: [LM139-SP](#), [LM139A-SP](#)

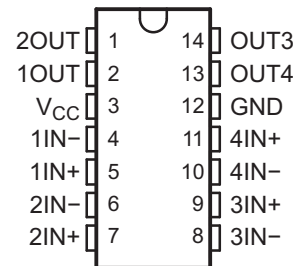
FEATURES

- QML-V Qualified, SMD 5962-7700801VCA, 5962-9673802VCA and 5962-9673802V9B
- Rad-Tolerant: 40 kRad/sec (Si) TID (5962-9673802VCA and 5962-9673802V9B) ⁽¹⁾
 - TID Dose Rate = 0.01 rad/sec (Si)
- Wide Supply Ranges
 - Single Supply: 2 V to 36 V (Tested to 30 V)
 - Dual Supplies: ± 1 V to ± 18 V (Tested to ± 15 V)
- Low Supply-Current Drain Independent of Supply Voltage: 0.8 mA (Typ)
- Low Input Bias Current: 25 nA (Typ)
- Low Input Offset Current: 3 nA (Typ) (LM139)
- Low Input Offset Voltage: 2 mV (Typ)

(1) Radiation tolerance is a typical value based upon initial device qualification with dose rate = 0.01 rad/sec. Radiation lot acceptance testing is available - contact factory for details.

- Common-Mode Input Voltage Range Includes Ground
- Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage: ± 36 V
- Low Output Saturation Voltage
- Output Compatible With TTL, MOS, and CMOS

**J PACKAGE
(TOP VIEW)**



DESCRIPTION/ORDERING INFORMATION

These devices consist of four independent voltage comparators that are designed to operate from a single power supply over a wide range of voltages. Operation from dual supplies also is possible, as long as the difference between the two supplies is 2 V to 36 V, and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. Current drain is independent of the supply voltage. The outputs can be connected to other open-collector outputs to achieve wired-AND relationships.

The LM139 and LM139A are characterized for operation over the full military temperature range of -55°C to 125°C .

Table 1. ORDERING INFORMATION ⁽¹⁾

T_A	V_{IOmax} AT 25°C	MAX V_{CC}	PACKAGE ⁽²⁾	ORDERABLE PART NUMBER		TOP-SIDE MARKING
-55°C to 125°C	5 mV	30 V	J	LM139	5962-7700801VCA	5962-7700801VCA
	2 mV	30 V		LM139A	5962-9673802VCA ⁽³⁾	5962-9673802VCA
	2 mV	30 V	KGD	5962-9673802V9B ⁽³⁾		N/A

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

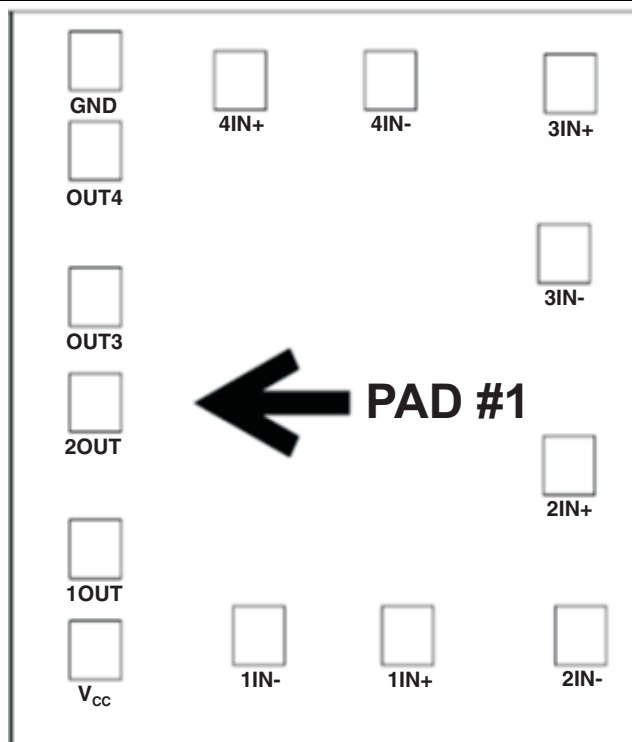
(3) Radiation tolerant



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

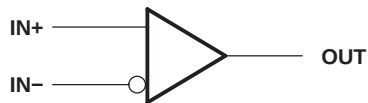
BARE DIE INFORMATION

DIE THICKNESS	BACKSIDE FINISH	BACKSIDE POTENTIAL	BON PAD METALLIZATION COMPOSITION	BOND PAD THICKNESS
15 mils	Silicon with backgrind	Floating	AlCu (0.5%)	0.055 mils

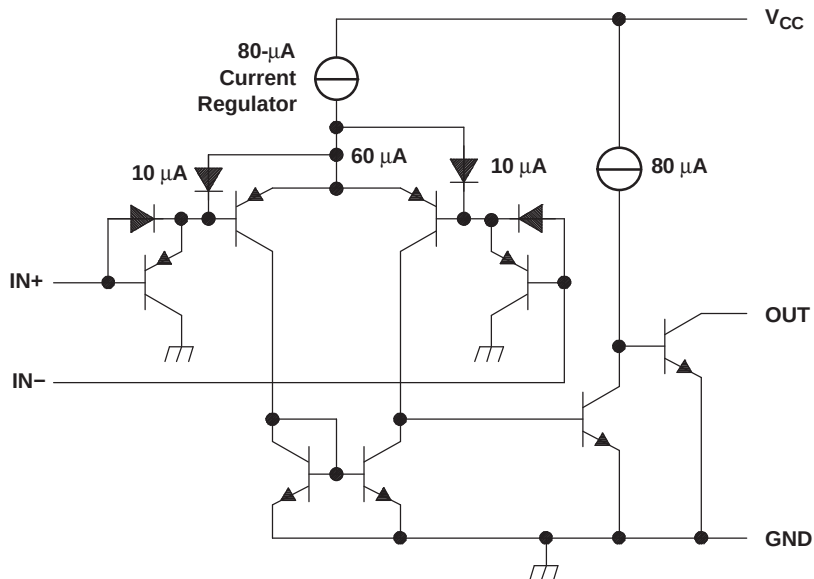
**Table 2. Bond Pad Coordinates in Microns**

DISCRIPTION	PAD NUMBER	Xmin	Ymin	Xmax	Ymax
2OUT	1	22.86	455.93	124.46	557.53
1OUT	2	22.86	203.2	124.46	304.8
Vcc	3	22.86	27.94	124.46	129.54
1IN-	4	345.44	53.34	447.04	154.94
1IN+	5	640.08	53.34	741.68	154.94
2IN-	6	981.71	53.34	1083.31	154.94
2IN+	7	958.85	347.98	1060.45	449.58
3IN-	8	948.69	713.74	1050.29	815.34
3IN+	9	961.39	1008.38	1062.99	1109.98
4IN-	10	605.79	1013.46	707.39	1115.06
4IN+	11	308.61	1013.46	410.21	1115.06
GND	12	22.86	1047.75	124.46	1149.35
OUT4	13	22.86	891.54	124.46	993.14
OUT3	14	22.86	638.81	124.46	740.41

SYMBOL (EACH COMPARATOR)



SCHEMATIC (EACH COMPARATOR)



All current values shown are nominal.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage ⁽²⁾			36	V
V _{ID}	Differential input voltage ⁽³⁾			±36	V
V _I	Input voltage range (either input)		–0.3	36	V
V _O	Output voltage			36	V
I _O	Output current			20	mA
	Duration of output short circuit to ground ⁽⁴⁾			Unlimited	
θ _{JC}	Package thermal impedance, junction to case ⁽⁵⁾ (6)	J package		15.05	°C/W
T _J	Operating virtual-junction temperature			150	°C
	Lead temperature 1,6 mm (1/16 in) from case for 60 s	J package		300	°C
T _{stg}	Storage temperature range		–65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential voltages, are with respect to network ground.
- (3) Differential voltages are at IN+ with respect to IN–.
- (4) Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.
- (5) Maximum power dissipation is a function of T_J (max), θ_{JC}, and T_C. The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J(\text{max}) - T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
- (6) The package thermal impedance is calculated in accordance with MIL-STD-883.

ELECTRICAL CHARACTERISTICS FOR LM139

at specified free-air temperature, $V_{CC} = 5\text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS ⁽¹⁾		T _A ⁽²⁾	MIN	TYP	MAX	UNIT	
V _{IO}	Input offset voltage	V _{CC} = 5 V to 30 V, V _{IC} = V _{ICR} min, V _O = 1.4 V		25°C	1			mV	
				Full range	4				
I _{IO}	Input offset current	V _O = 1.4 V		25°C	3			25	nA
				Full range	100				
I _{IB}	Input bias current	V _O = 1.4 V		25°C	−25			−100	nA
				Full range	−300				
V _{ICR}	Common-mode input-voltage range ⁽³⁾			25°C	0 to V _{CC} − 1.5			V	
				Full range	0 to V _{CC} − 2				
A _{VD}	Large-signal differential-voltage amplification	V _{CC+} = ±7.5 V, V _O = −5 V to 5 V		25°C	50	200		V/mV	
I _{OH}	High-level output current	V _{ID} = 1 V	V _{OH} = 5 V	25°C	0.1			nA	
			V _{OH} = 30 V	Full range	1			μA	
V _{OL}	Low-level output voltage	V _{ID} = −1 V, I _{OL} = 4 mA		25°C	150			400	mV
				Full range	700				
I _{OL}	Low-level output current	V _{ID} = −1 V,	V _{OL} = 1.5 V	25°C	6	16		mA	
I _{CC}	Supply current (four comparators)	V _O = 2.5 V,	No load	25°C	0.8			2	mA

(1) All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

(2) Full range (MIN to MAX) for LM139 and LM139A is –55°C to 125°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

(3) The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is $V_{CC+} - 1.5\text{ V}$; however, one input can exceed V_{CC+} , and the comparator will provide a proper output state as long as the other input remains in the common-mode range. Either or both inputs can go to 30 V without damage.

ELECTRICAL CHARACTERISTICS FOR LM139Aat specified free-air temperature, $V_{CC} = 5\text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS ⁽¹⁾	T_A ⁽²⁾	MIN	TYP ⁽³⁾	MAX	UNIT
I_{CC}	Supply current	$R_L = \infty$, $V_+ = 30\text{ V}$	Full range			2	mA
I_{CEX}	Output leakage current	$V_+ = 30\text{ V}$, $V_{OUT} = 30\text{ V}$	Full range			1	μA
V_{SAT}	Saturation voltage	$I_{SINK} = 4\text{ mA}$	25°C			400	mV
			Full range			700	
I_{SINK}	Output sink current	$V_{OUT} = 1.5\text{ V}$	25°C		6		mA
V_{IO}	Input offset voltage	$V_+ = 5\text{ V}$, $V_{CM} = 0\text{ V}$	25°C			± 2	mV
			Full range			± 4	
		$V_+ = 30\text{ V}$, $V_{CM} = 0\text{ V}$	25°C			± 2	mV
			Full range			± 4	
		$V_+ = 30\text{ V}$, $V_{CM} = 28.5\text{ V}$, $V_{OUT} = 1.5\text{ V}$	25°C			± 2	mV
		$V_+ = 30\text{ V}$, $V_{CM} = 28\text{ V}$, $V_{OUT} = 1.5\text{ V}$	Full range			± 4	mV
I_{IB}	Input bias current	$V_{OUT} = 1.5\text{ V}$	25°C	-100		-1	nA
			Full range	-300		-1	
I_{IO}	Input offset current	$V_{OUT} = 1.5\text{ V}$	25°C			± 25	nA
			Full range			± 100	
PSRR	Power supply rejection ratio	$V_+ = 5\text{ V}$ to 30 V	25°C	60		100	dB
CMRR	Common-mode rejection ratio	$V_+ = 30\text{ V}$, $V_{CM} = 0\text{ V}$ to 28.5 V	25°C	60			dB
A_V	Voltage gain	$V_+ = 15\text{ V}$, $R_L \geq 15\text{ k}\Omega$, $V_{OUT} = 1\text{ V}$ to 11 V	25°C	50			V/mV
$V_{CM}^{(4)}$	Common mode voltage range	$V_+ = 30\text{ V}$	25°C	0		$V_+ - 1.5$	V
			Full range	0		$V_+ - 2$	
$V_{DIFF}^{(5)}$	Differential input voltage	$V_+ = 30\text{ V}$, $V_- = 0\text{ V}$, $V_{IN+} = 36\text{ V}$, $V_{IN-} = 0\text{ V}$	Full range			500	nA
		$V_+ = 30\text{ V}$, $V_- = 0\text{ V}$, $V_{IN+} = 0\text{ V}$, $V_{IN-} = 36\text{ V}$				500	
t_{RLH}	Response time	$V_{OD}(\text{overdrive}) = 5\text{ mV}$	25°C			5	μs
		$V_{OD}(\text{overdrive}) = 50\text{ mV}$				0.8	
t_{RHL}	Response time	$V_{OD}(\text{overdrive}) = 5\text{ mV}$	25°C			2.5	μs
		$V_{OD}(\text{overdrive}) = 50\text{ mV}$				0.8	

- (1) All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified. MAX V_{CC} for testing purposes is 30 V.
- (2) Full range is -55°C to 125°C for LM139A.
- (3) All typical values are at $T_A = 25^\circ\text{C}$.
- (4) The input common mode voltage or either input signal voltage should not be allowed to go negative by more than 0.3 V. The upper end of the common mode voltage range is $V_+ - 1.5\text{ V}$ for $T_A = 25^\circ\text{C}$ or $V_+ - 2.0\text{ V}$ for $T_A = \text{Full range}$, but either or both inputs can go to +30 V dc without damage independent of the magnitude of V_+ .
- (5) Positive excursions of input voltage may exceed the power supply level. As long as the other voltage remains within the common mode range, the comparator will provide a proper output state. The low input voltage state must not be less than -0.3 V dc or 0.3 V dc below the magnitude of the negative power supply, if used.

SWITCHING CHARACTERISTICS

 $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

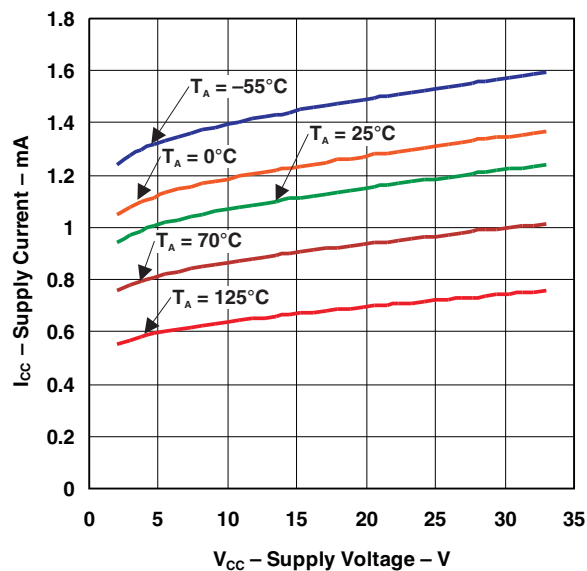
PARAMETER	TEST CONDITIONS		TYP	UNIT
Response time	R_L connected to 5 V through 5.1 k Ω , $C_L = 15\text{ pF}^{(1)}\text{ }^{(2)}$	100-mV input step with 5-mV overdrive	1.3	μs
		TTL-level input step	0.3	

(1) C_L includes probe and jig capacitance.

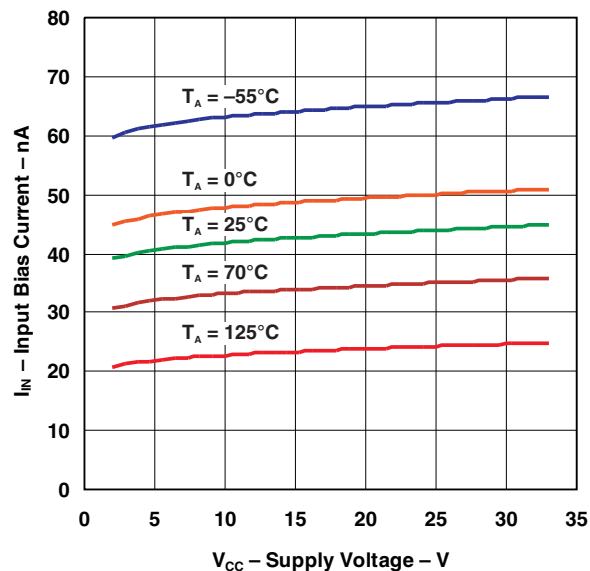
(2) The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

TYPICAL CHARACTERISTICS

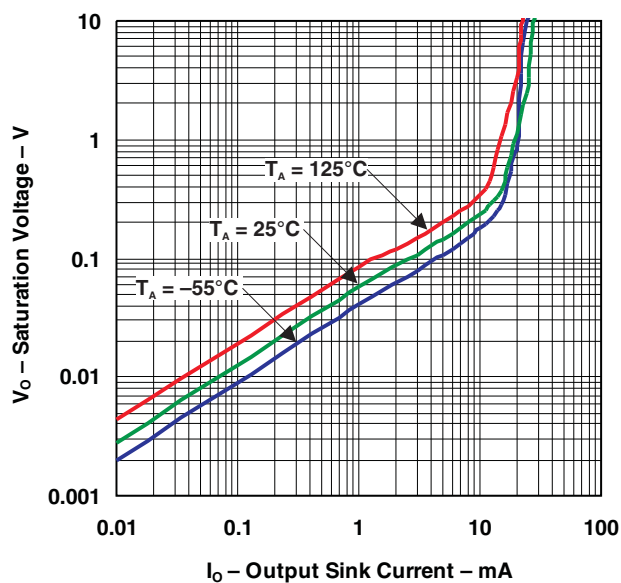
SUPPLY CURRENT
vs
SUPPLY VOLTAGE



INPUT BIAS CURRENT
vs
SUPPLY VOLTAGE

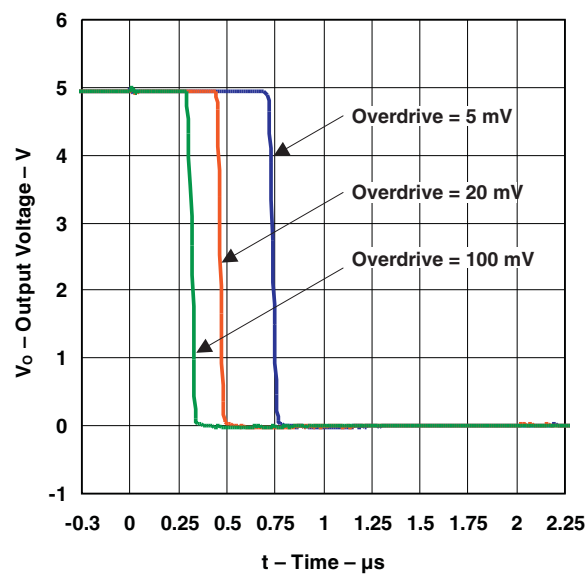


OUTPUT SATURATION VOLTAGE

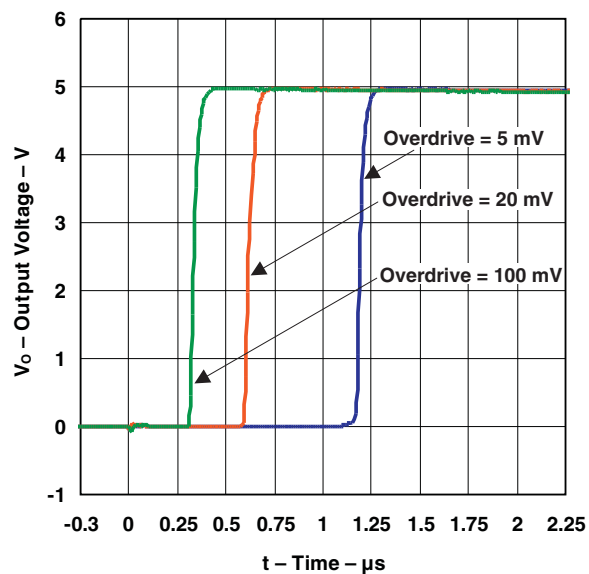


TYPICAL CHARACTERISTICS (continued)

RESPONSE TIME FOR VARIOUS OVERDRIVES
NEGATIVE TRANSITION



RESPONSE TIME FOR VARIOUS OVERDRIVES
POSITIVE TRANSITION



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-7700801VCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
5962-9673802V9B	ACTIVE	XCEPT	KGD	0	100	TBD	Call TI	N / A for Pkg Type	
5962-9673802VCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF LM139-SP :

- Catalog: [LM139](#)

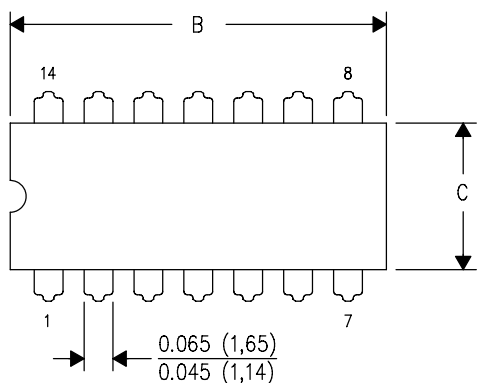
NOTE: Qualified Version Definitions:

-
- Catalog - TI's standard catalog product

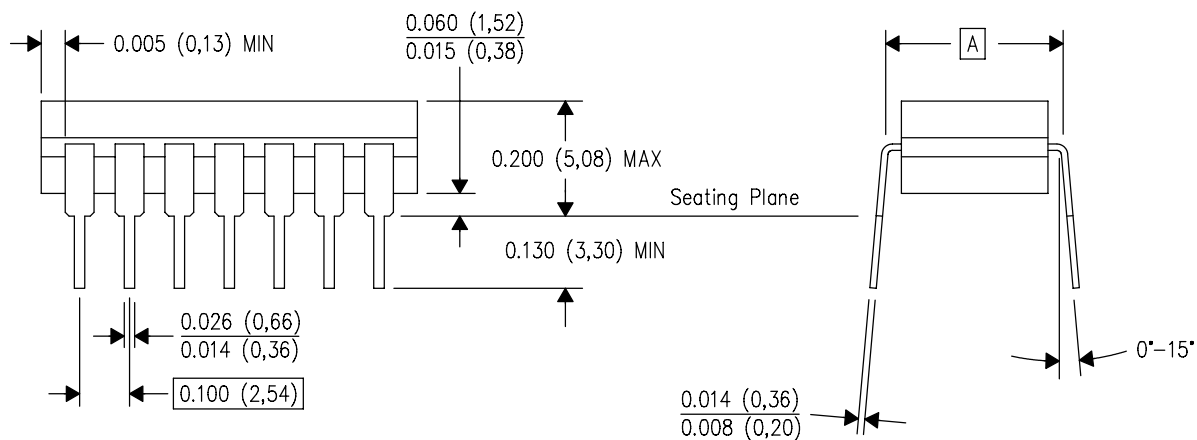
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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